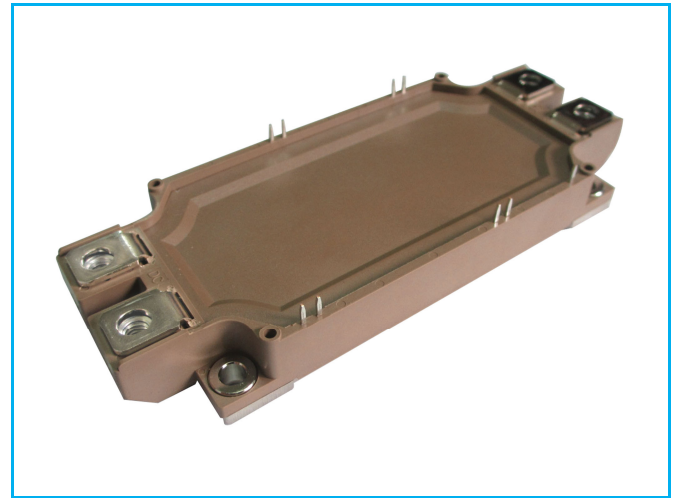


## PRODUCT FEATURES

- IGBT3 CHIP(1700V Trench+Field Stop technology)
- Low turn-off losses, short tail current
- $V_{CE(sat)}$  with positive temperature coefficient
- DIODE CHIP(1700V EMCON 3 technology)
- Free wheeling diodes with fast and soft reverse recovery



## APPLICATIONS

- High frequency switching application
- Medical applications
- Motion/servo control
- UPS systems

### IGBT-inverter

ABSOLUTE MAXIMUM RATINGS( $T_C=25^{\circ}C$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$V_{CES}$	Collector Emitter Voltage	$T_J=25^{\circ}C$	1700	V
$V_{GES}$	Gate Emitter Voltage		$\pm 20$	
$I_C$	DC Collector Current	$T_C=25^{\circ}C, T_{Jmax}=175^{\circ}C$	230	A
		$T_C=95^{\circ}C, T_{Jmax}=175^{\circ}C$	150	
$I_{CM}$	Repetitive Peak Collector Current	$t_p=1ms$	300	
$P_{tot}$	Power Dissipation Per IGBT	$T_C=25^{\circ}C, T_{Jmax}=175^{\circ}C$	1250	W

### Diode-inverter

ABSOLUTE MAXIMUM RATINGS ( $T_C=25^{\circ}C$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$V_{RRM}$	Repetitive Reverse Voltage	$T_J=25^{\circ}C$	1700	V
$I_{F(AV)}$	Average Forward Current		150	A
$I_{FRM}$	Repetitive Peak Forward Current	$t_p=1ms$	300	
$I^2t$		$T_J=125^{\circ}C, t=10ms, V_R=0V$	3800	$A^2S$

MacMic Science & Technology Co., Ltd.

Add: #18, Hua Shan Zhong Lu, New District, Changzhou City, Jiangsu Province, P. R .of China

# MMG150WB170H6EN

## IGBT-inverter

### ELECTRICAL CHARACTERISTICS ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
$V_{GE(th)}$	Gate Emitter Threshold Voltage	$V_{CE}=V_{GE}, I_C=6\text{mA}$	5.2	5.8	6.4	V
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	$I_C=150\text{A}, V_{GE}=15\text{V}, T_J=25^\circ\text{C}$		2	2.45	
		$I_C=150\text{A}, V_{GE}=15\text{V}, T_J=125^\circ\text{C}$		2.4		
$I_{CES}$	Collector Leakage Current	$V_{CE}=1700\text{V}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$			3	mA
		$V_{CE}=1700\text{V}, V_{GE}=0\text{V}, T_J=125^\circ\text{C}$			20	mA
$I_{GES}$	Gate Leakage Current	$V_{CE}=0\text{V}, V_{GE}=\pm 15\text{V}, T_J=25^\circ\text{C}$	-400		400	nA
$R_{gint}$	Integrated Gate Resistor			5		$\Omega$
$Q_g$	Gate Charge	$V_{CE}=900\text{V}, I_C=150\text{A}, V_{GE}=\pm 15\text{V}$		1.7		$\mu\text{C}$
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$		13.5		nF
$C_{res}$	Reverse Transfer Capacitance				450	
$t_{d(on)}$	Turn on Delay Time	$V_{CC}=900\text{V}, I_C=150\text{A}$ $R_G=9.1\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	280		ns
			$T_J=125^\circ\text{C}$	300		ns
$t_r$	Rise Time	$V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	50		ns
			$T_J=125^\circ\text{C}$	66		ns
$t_{d(off)}$	Turn off Delay Time	$V_{CC}=900\text{V}, I_C=150\text{A}$ $R_G=9.1\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	810		ns
			$T_J=125^\circ\text{C}$	1000		ns
$t_f$	Fall Time	$V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	180		ns
			$T_J=125^\circ\text{C}$	300		ns
$E_{on}$	Turn on Energy	$V_{CC}=900\text{V}, I_C=150\text{A}$ $R_G=9.1\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	33		mJ
			$T_J=125^\circ\text{C}$	48		mJ
$E_{off}$	Turn off Energy	$V_{GE}=\pm 15\text{V},$ Inductive Load	$T_J=25^\circ\text{C}$	32		mJ
			$T_J=125^\circ\text{C}$	47		mJ
$I_{SC}$	Short Circuit Current	$tp_{sc} \leq 10\mu\text{s}, V_{GE}=15\text{V}$ $T_J=125^\circ\text{C}, V_{CC}=1000\text{V}$		600		A
$R_{thJC}$	Junction to Case Thermal Resistance ( Per IGBT )				0.12	K /W

## Diode-inverter

### ELECTRICAL CHARACTERISTICS ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit
$V_F$	Forward Voltage	$I_F=150\text{A}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$		1.8	2.2	V
		$I_F=150\text{A}, V_{GE}=0\text{V}, T_J=125^\circ\text{C}$		1.9		
$t_{rr}$	Reverse Recovery Time	$I_F=150\text{A}, V_R=900\text{V}$ $di_F/dt=-2150\text{A}/\mu\text{s}$ $T_J=125^\circ\text{C}$		550		ns
$I_{RRM}$	Max. Reverse Recovery Current			190		A
$Q_{RR}$	Reverse Recovery Charge			65.5		$\mu\text{C}$
$E_{rec}$	Reverse Recovery Energy			36		mJ
$R_{thJCD}$	Junction to Case Thermal Resistance ( Per Diode )				0.21	K /W

# MMG150WB170H6EN

MODULE CHARACTERISTICS ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter/Test Conditions		Values	Unit
$T_{Jmax}$	Max. Junction Temperature		175	°C
$T_{Jop}$	Operating Temperature		-40~150	
$T_{stg}$	Storage Temperature		-40~125	
$V_{isol}$	Isolation Breakdown Voltage	AC, 50Hz(R.M.S), $t=1$ minute	4000	V
Torque	to heatsink	Recommended (M5)	2.5~5	Nm
	to terminal	Recommended (M6)	3~5	Nm
Weight			350	g

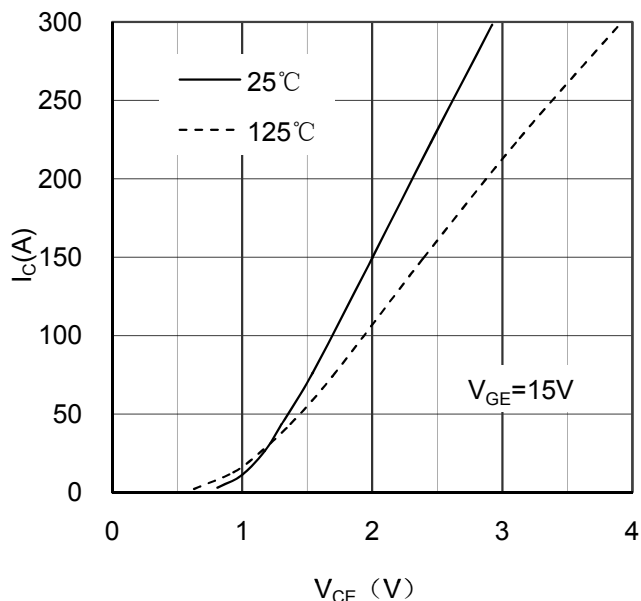


Figure 1. Typical Output Characteristics IGBT-inverter

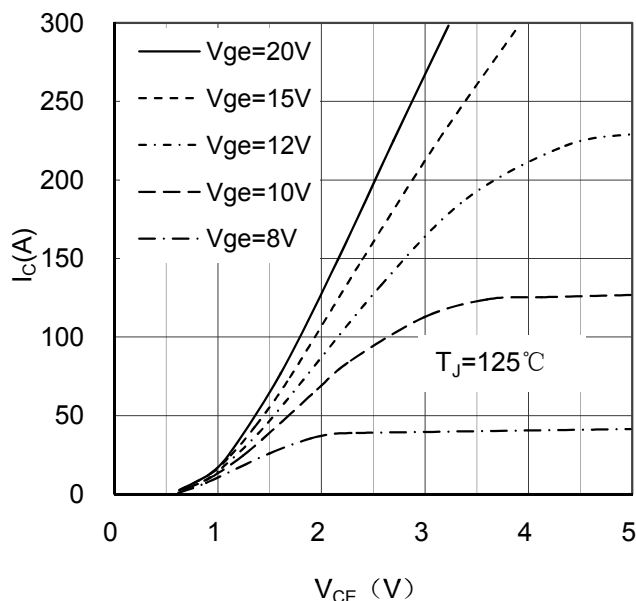


Figure 2. Typical Output Characteristics IGBT-inverter

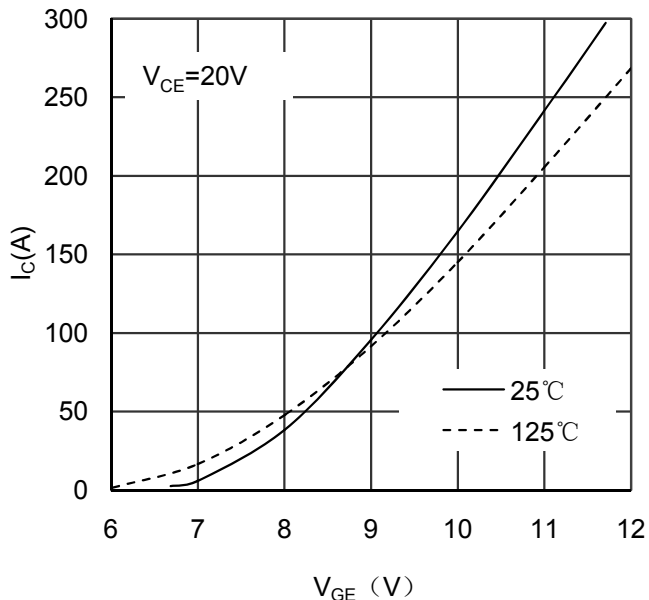


Figure 3. Typical Transfer characteristics IGBT-inverter

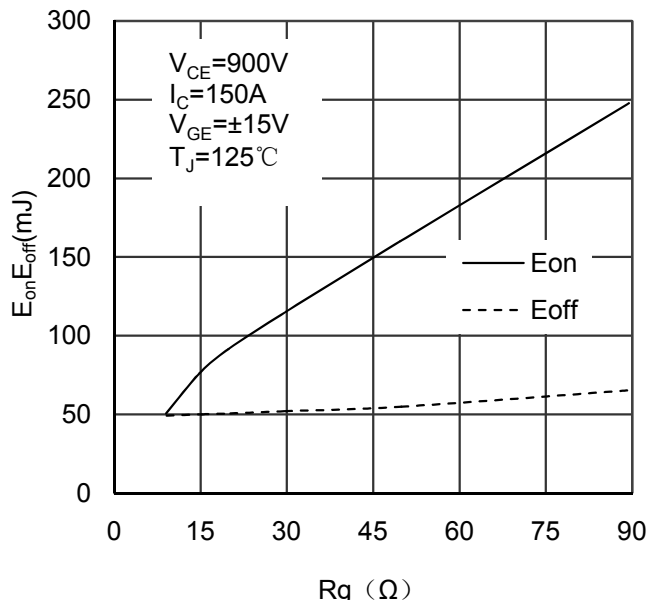


Figure 4. Switching Energy vs Gate Resistor IGBT-inverter

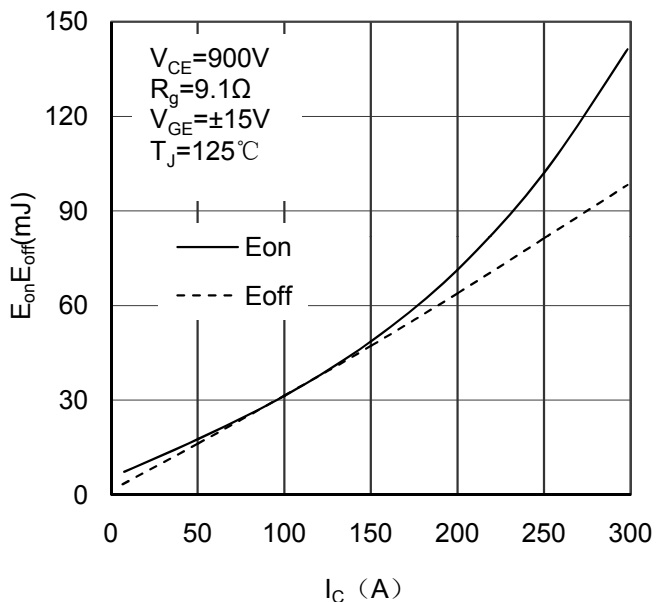


Figure 5. Switching Energy vs Collector Current IGBT-inverter

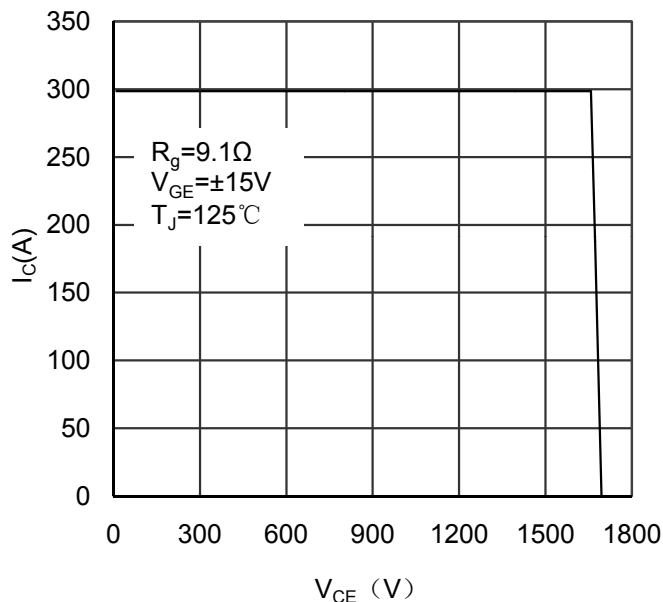


Figure 6. Reverse Biased Safe Operating Area IGBT-inverter

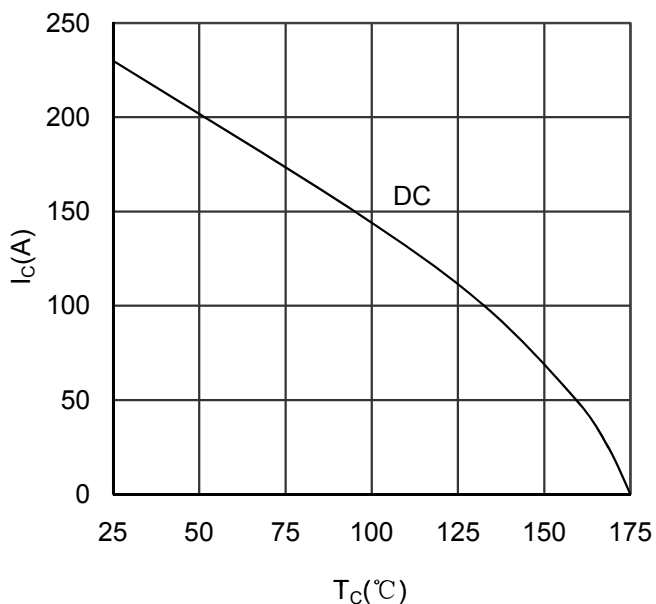


Figure 7. Collector Current vs Case temperature IGBT -inverter

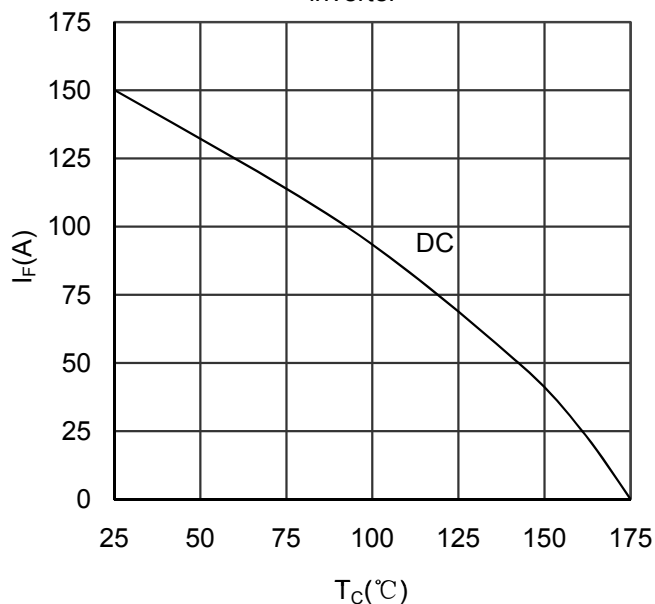


Figure 8. Forward current vs Case temperature Diode -inverter

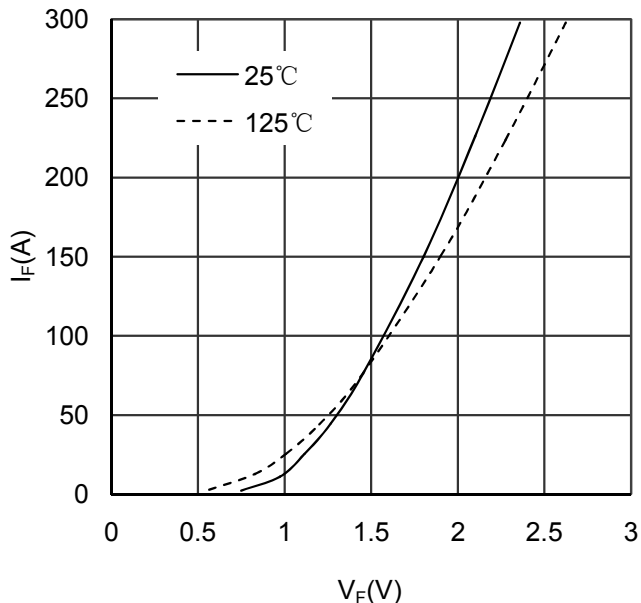


Figure 9. Diode Forward Characteristics Diode -inverter

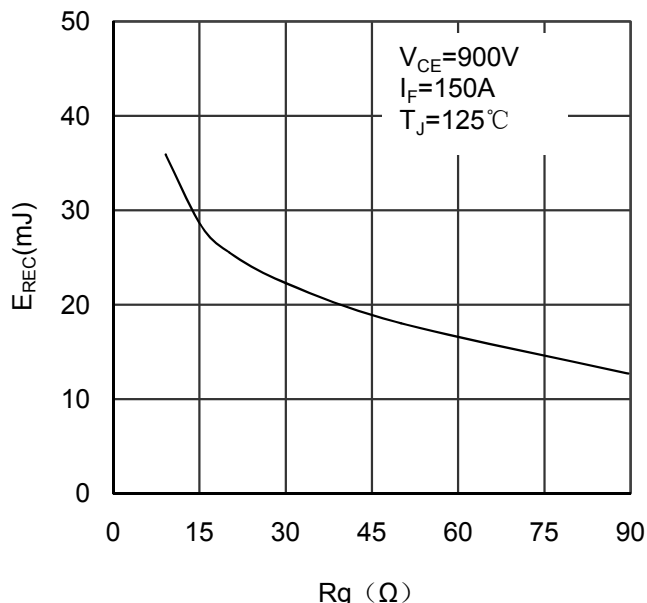


Figure 10. Switching Energy vs Gate Resistor Diode - inverter

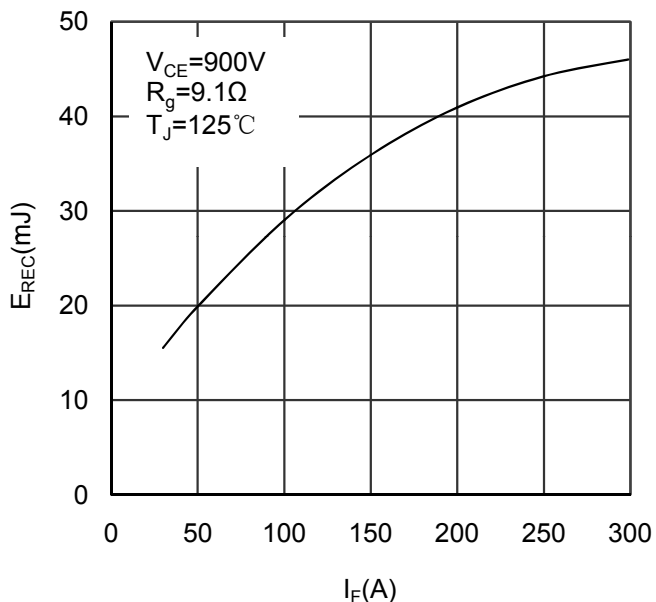


Figure 11. Switching Energy vs Forward Current Diode-inverter

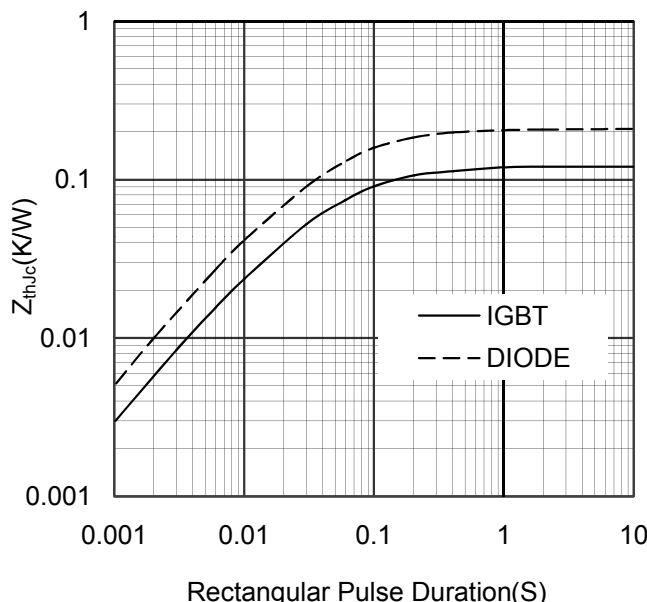


Figure 12. Transient Thermal Impedance of Diode and IGBT-inverter

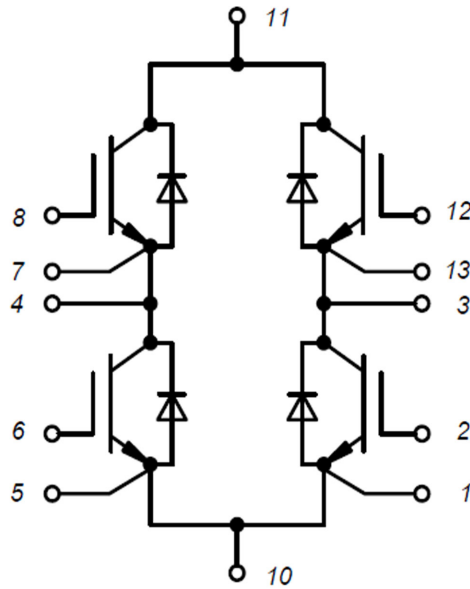
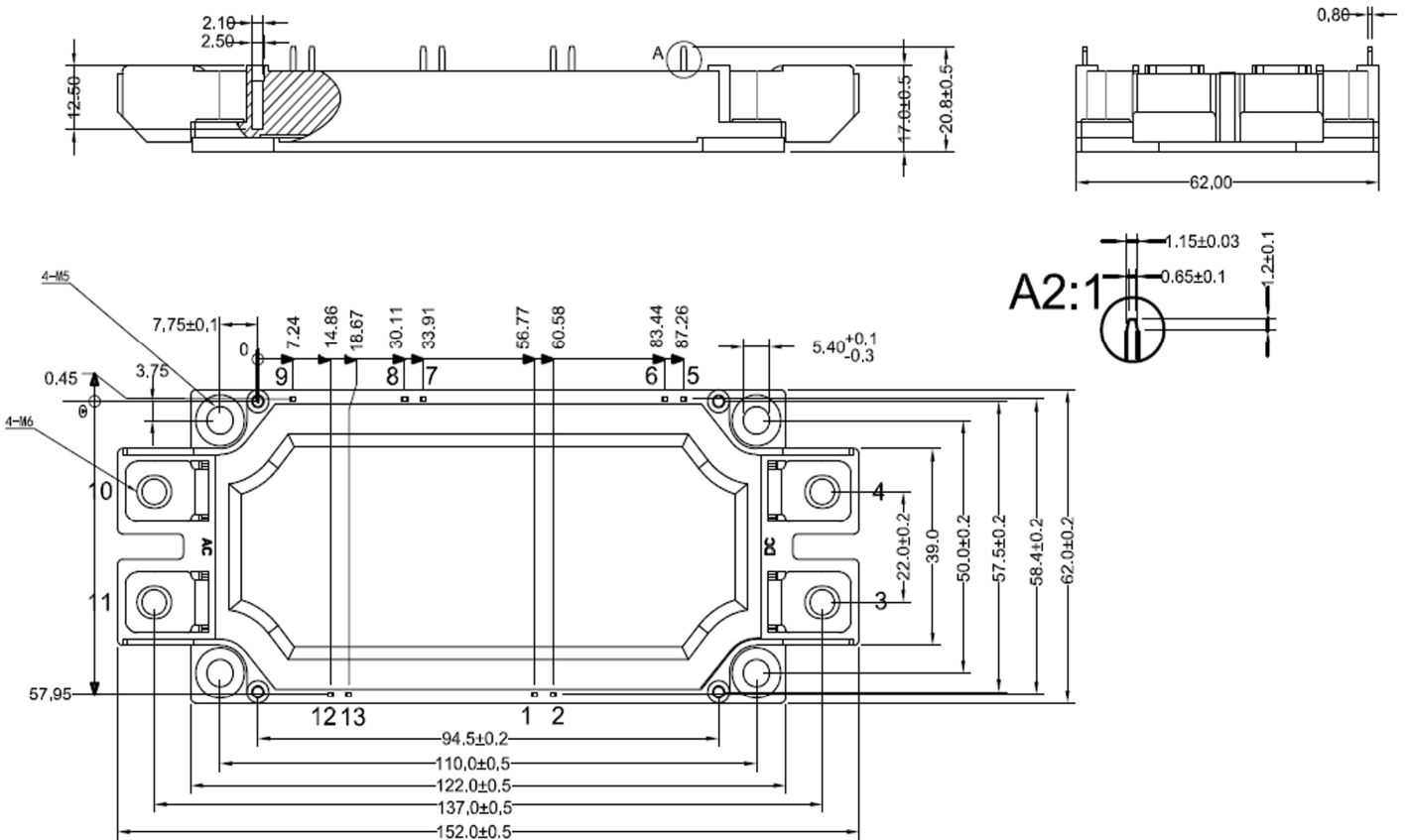


Figure 13. Circuit Diagram



Dimensions in (mm)

Figure 14. Package Outline